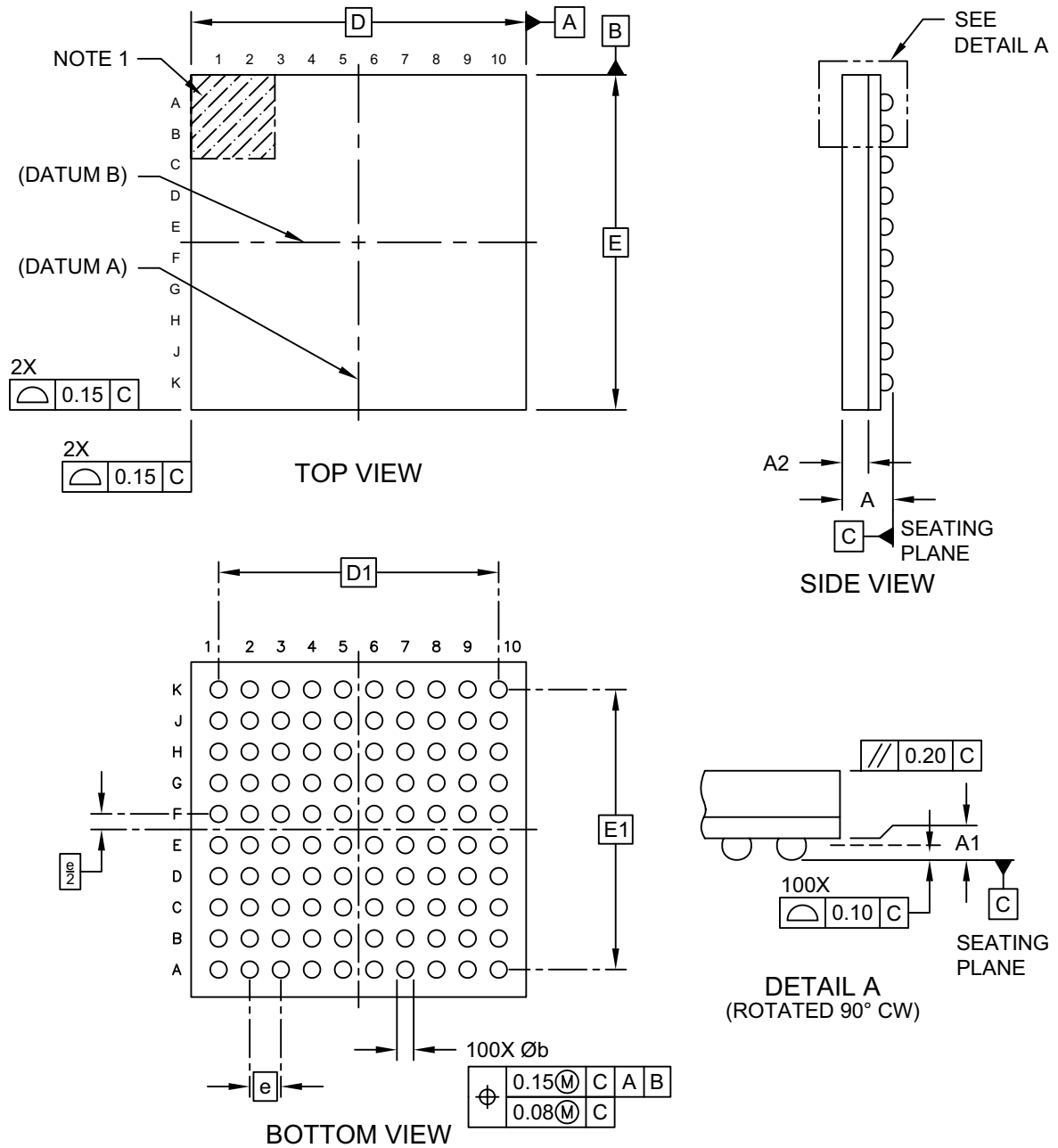


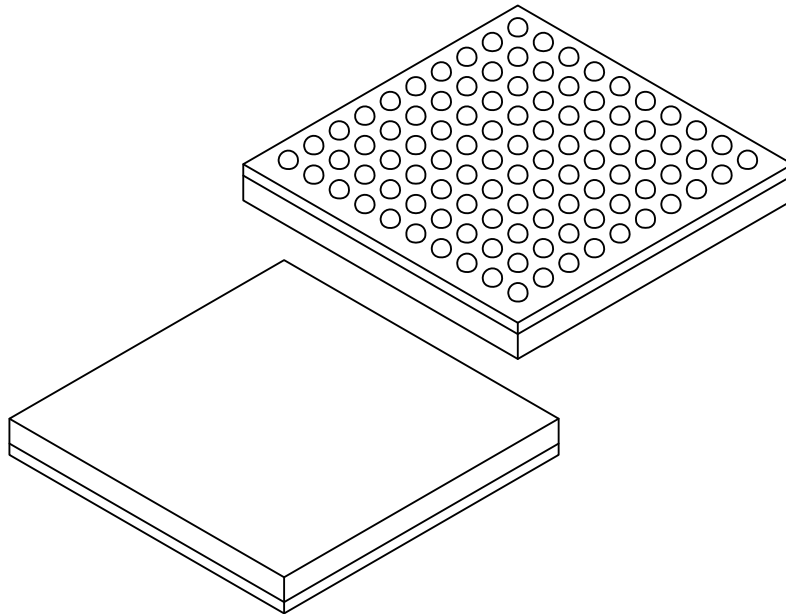
100-Ball Thin Fine Pitch Ball Grid Array (GJX) - 7x7 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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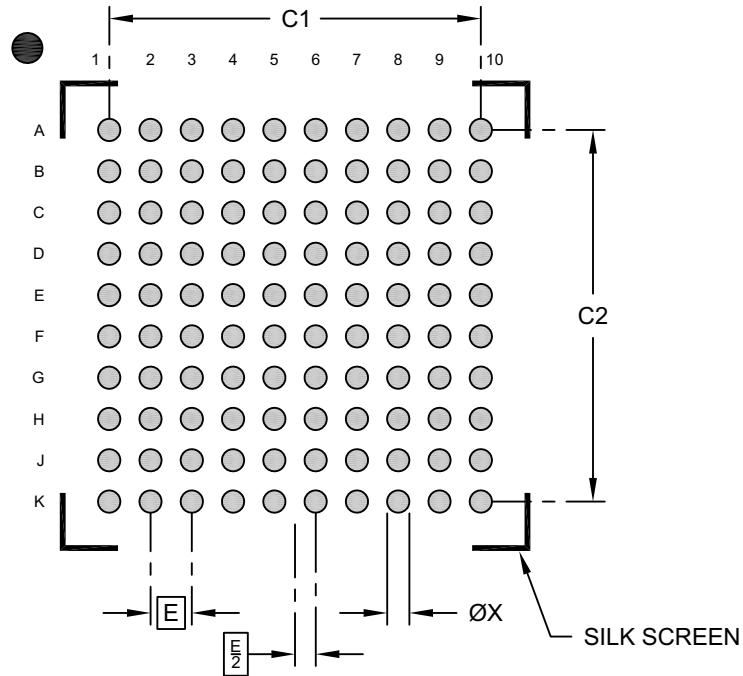
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	100		
Pitch	e	0.65 BSC		
Overall Height	A	-	-	1.06
Ball Height	A1	0.18	0.26	-
Mold Cap Height	A2	0.45	0.50	0.55
Overall Length	D	7.00 BSC		
Overall Pitch	D1	5.85 BSC		
Overall Width	E	7.00 BSC		
Overall Pitch	E1	5.85 BSC		
Terminal Width	b	0.30	0.35	0.40

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

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Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Diameter	X		0.35	
Contact Pad Spacing	C1		5.85	
Contact Pad Spacing	C2		5.85	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.